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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: West et al. Docket No.: TI-36238  
Serial No.: 10/697,137 Examiner: Guerrero, M.  
Filing Date: 10/30/2003 Art Unit: 2822  
Customer No.: 23494 Conf. No.: 9756  
Title: METHOD FOR IMPROVING RELIABILITY OF COPPER INTERCONNECTS

TRANSMITTAL OF FORMAL DRAWINGS

Commissioner for Patents  
P. O. Box 1450  
Alexandria, VA 22313-1450

Attn: Official Draftsperson

Dear Sir:

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)  
I hereby certify that the above correspondence is being  
deposited with the U.S. Postal Service as First Class Mail  
in an envelope addressed to: Commissioner of Patents,  
P. O. Box 1450, Alexandria, VA 22313-1450.

12-2-05  
Date: Marianna Smith  
Marianna Smith

Submitted herewith are three (3) sheets of formal drawings.

Charge any necessary fee to Deposit Account No. 20-0668. The original and a  
copy of this authorization are enclosed.

Respectfully submitted,

Jacqueline J. Garner  
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